



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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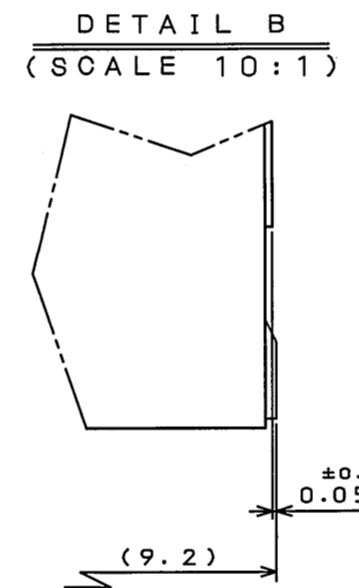
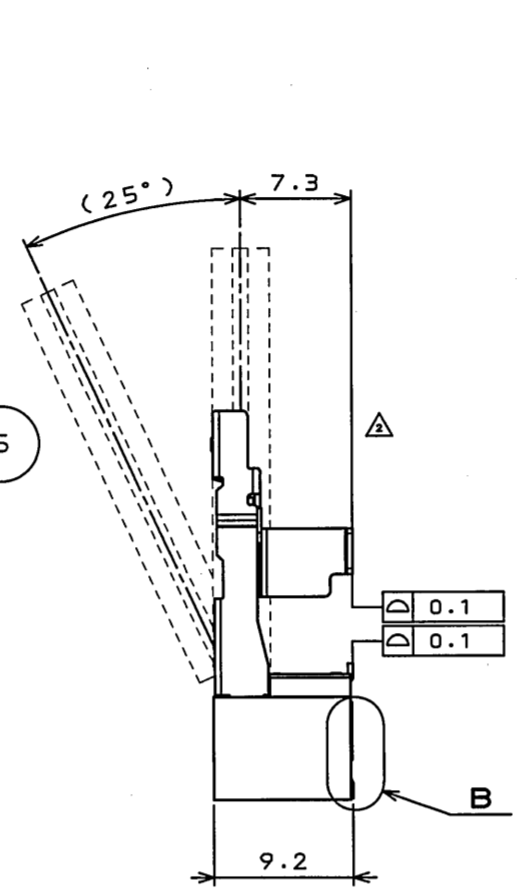
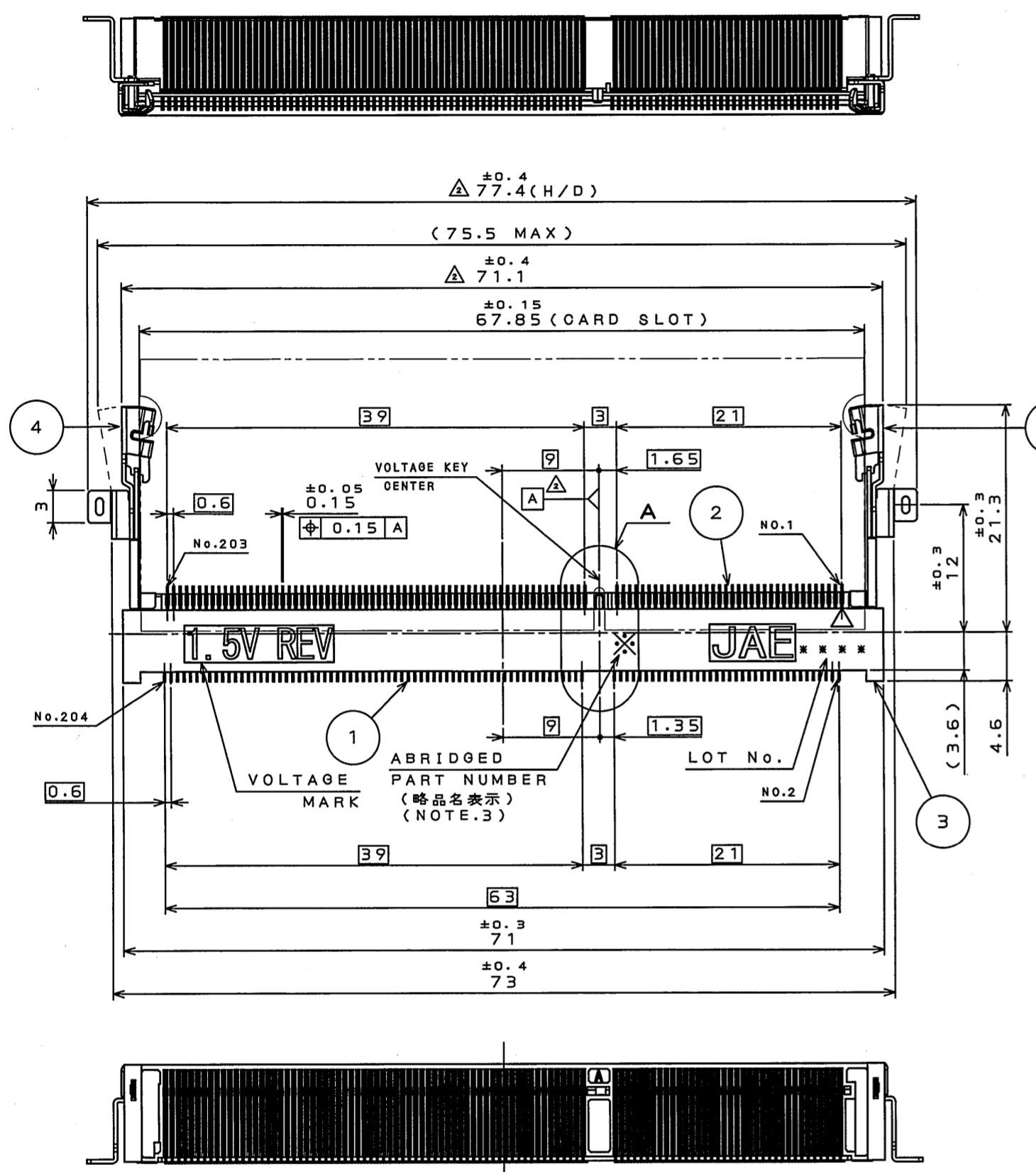
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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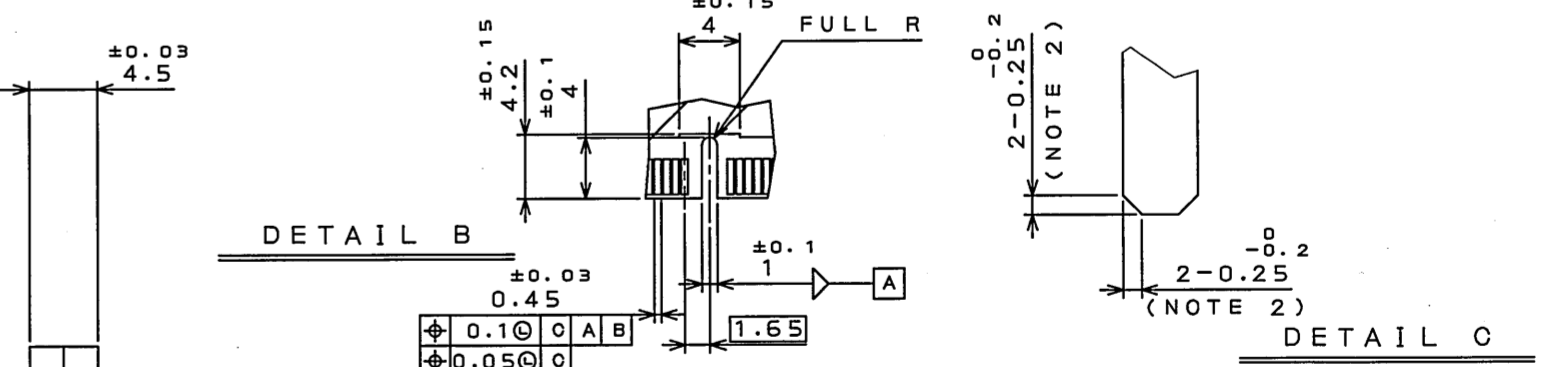
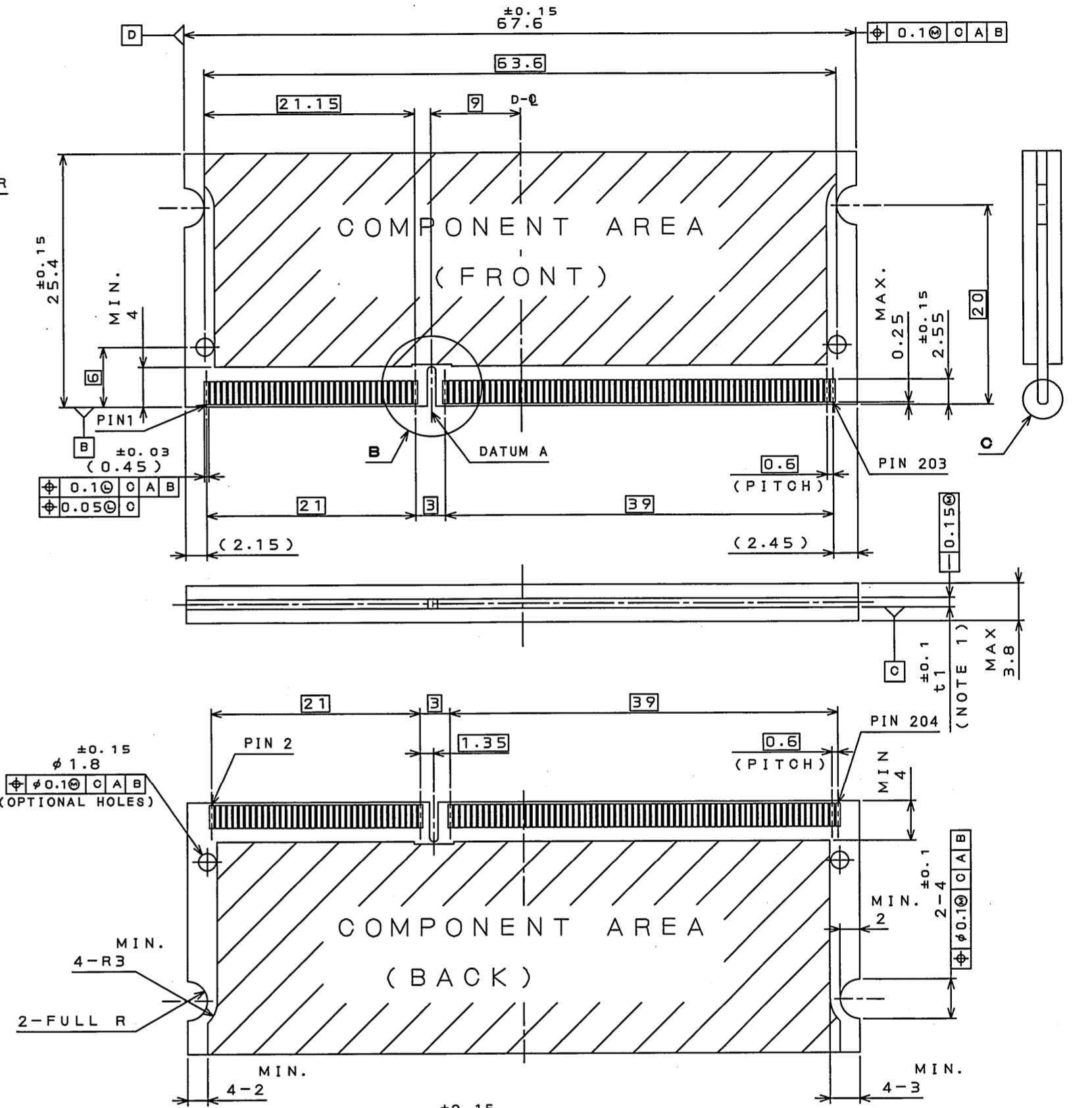


版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	10.Feb.2011	071605	LATCH SHAPE CHANGE AND GEOMETRY ALLOWANCE ADD		R.KATOU		T.Shindou

APPLICABLE DIMM(REF.)



APPLICABLE P.C.B. DIMENSION(REF.)  
適合基板寸法(参考)

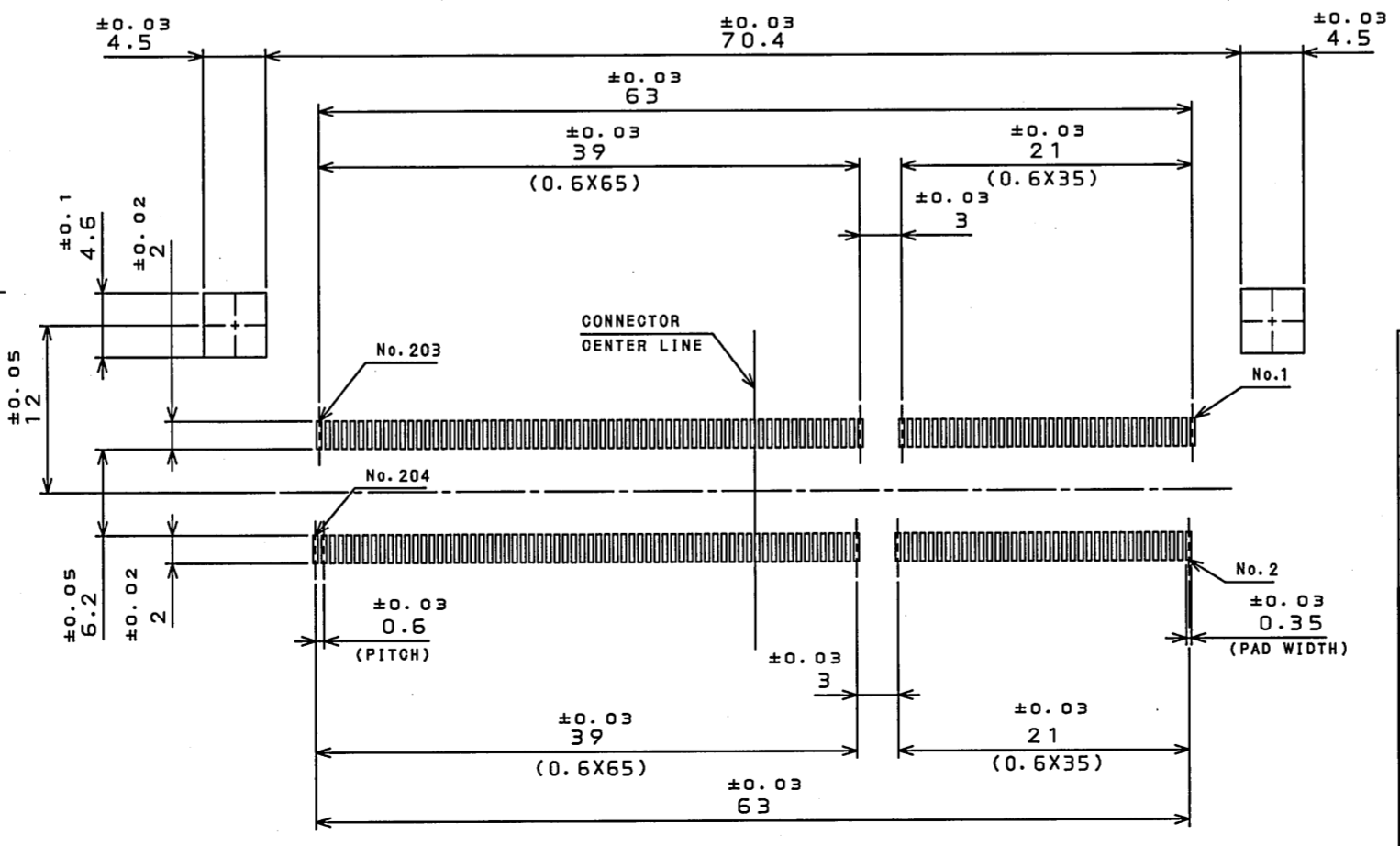


DESIGNATION

MM80-204B1-E1R	R : REVERSE NONE : STANDARD
SERIES シリーズ	CONTACT FINISH 接点仕上げ 1:Au(0.1μm MIN) OVER NI
NO. OF CONTACTS 芯数	MODIFY CODE モディファイコード E:9.2mm HEIGHT
SOCKET TYPE ソケットタイプ B:LATCH TYPE SMT	KEYING TYPE キタイフ 1:1.5V

NOTE 1. CARD THICKNESS INCLUDES PAD PLATING.  
NOTE 2. BEVEL MUST BE FREE OF CUTTING BURRS.  
NOTE 3. ABRIDGED PART NUMBER IS DISPLAYED AS BELOW  
MM80-204B1-E1R  
ABRIDGED PART NUMBER

注1. カートの厚みは、接点部パッドのめっきを含んだ厚みを適用します。  
注2. 先端面取り部は、バリなど無き事。  
注3. 略品名表示は下記下線部分を表示します。  
MM80-204B1-E1R  
略品名



符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
5	LATCH 2	1	STAINLESS	TIN PLATING	
4	LATCH 1	1	STAINLESS	TIN PLATING	
3	INSULATOR	1	GLASS FILLED LCP		
2	LOWER CONTACT	102	COPPER ALLOY	CONTACT AREA:Au(0.1μm MIN) OVER NICKEL SOLDERING AREA:BOLD FLASH OVER NICKEL	
1	UPPER CONTACT	102	COPPER ALLOY	CONTACT AREA:Au(0.1μm MIN) OVER NICKEL SOLDERING AREA:BOLD FLASH OVER NICKEL	

仕様書(SPECIFICATION) JACS-10662	第1版(ORIGINAL DATE) 24.AUG.2010	版数(SOALE) 2:1	シリーズ(SERIES) MM80	備考 日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
公差(GENERAL TOLERANCE) 寸法(DIMENSION) 角度(ANGLES)	製図 DR. R.KATOU	名称(TITLE) MM80-204B1-E1R	図面番号(DRAWING NO.) SJ110282	版数(REV.) 2
. ±0.8 .X ±0.4 .XX ±0.1 .XXX ±	承認 APPD. T.SHINDOU	質量(MASS)		